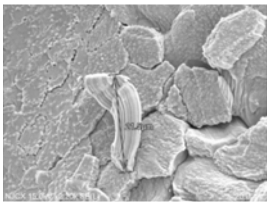
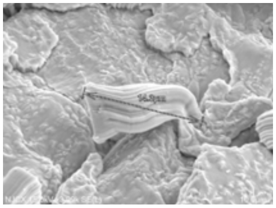
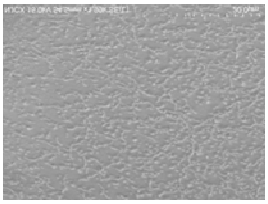
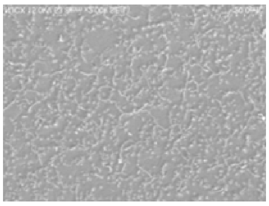
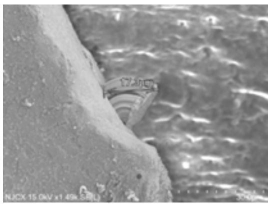
Report NO.: TW-0001

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Package List	TO-251/252/277 Series.TO-220/220F/263/247/3P Series. SOT-23/223/89/353/363/523/723/923 Series. SOD-123/323/523/723 Series; WBFBP Series; DFN/PDFN/QFN Series; TOLL/sTOLL Series. SMA/B/C Series; TSSOP Series; SOP/ESOP Series.
Substrate Material	Cu Alloy & FeNi Alloy
Test Standard	JESD201A & JESD22A121
Samples Size	A minimum of 96 terminations from a minimum quantity of 3 plating lots, 2 samples from each lot per each described precondition treatments per stress test.
Plating Process	Matte tin
Surface finish thickness	5~20μm
Surface finish Alloy	Sn 99.99%

2. Test Result:PASS

Test Items	Test Conditions	Acceptance Criteria	Test Result	Remark
Temperature Cycling(TC)	-55℃～85℃,10 min soak, 30min/cycle 1500Cycles	≤45μm	PASS	Class2
Temperature/Humidity Storage(THT)	30℃/60%RH 4000h	≤40μm	PASS	Class2
High Temperature/Humidity Storage(THT&H)	55℃/85%RH 4000h	≤40μm	PASS	Class2
				
TC:	21.5μm (Max)	14.3μm		
				
THT:	No Whisker	No Whisker		
				
THT&H:	17.3μm (Max)	10.6μm		

Remark: JSCJ Laboratory reserves the right of final interpretation of this report